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CY23S08

3.3V Zero Delay Buffer

Features

- Zero input-output propagation delay, adjustable by capacitive load on FBK input
- Multiple configurations, see *Table 3* on page 3
- Multiple low-skew outputs
  - 45 ps typical output-output skew(–1)
  - Two banks of four outputs, three-stateable by two select inputs
- 10 MHz to 133 MHz operating range
- 65 ps typical cycle-cycle jitter (–1, –1H)
- Advanced 0.65µ CMOS technology
- Space saving 16-pin 150-mil SOIC/TSSOP packages
- 3.3V operation
- Spread Aware™

Functional Description

The CY23S08 is a 3.3V zero delay buffer designed to distribute high speed clocks in PC, workstation, datacom, telecom, and other high performance applications.

The part has an on-chip PLL which locks to an input clock presented on the REF pin. The PLL feedback must be driven into the FBK pin, and can be obtained from one of the outputs. The input-to-output propagation delay is guaranteed to be less than 350 ps, and output-to-output skew is guaranteed to be less than 250 ps.

The CY23S08 has two banks of four outputs each, which can be controlled by the Select inputs as shown in *Table 2* on page 3. If all output clocks are not required, Bank B can be three-stated. The select inputs also allow the input clock to be directly applied to the output for chip and system testing purposes.

The CY23S08 PLL enters a power down state when there are no rising edges on the REF input. In this mode, all outputs are three-stated and the PLL is turned off, resulting in less than 50 µA of current draw. The PLL shuts down in two additional cases as shown in *Table 2* on page 3.

Multiple CY23S08 devices can accept the same input clock and distribute it in a system. In this case, the skew between the outputs of two devices is guaranteed to be less than 700 ps.

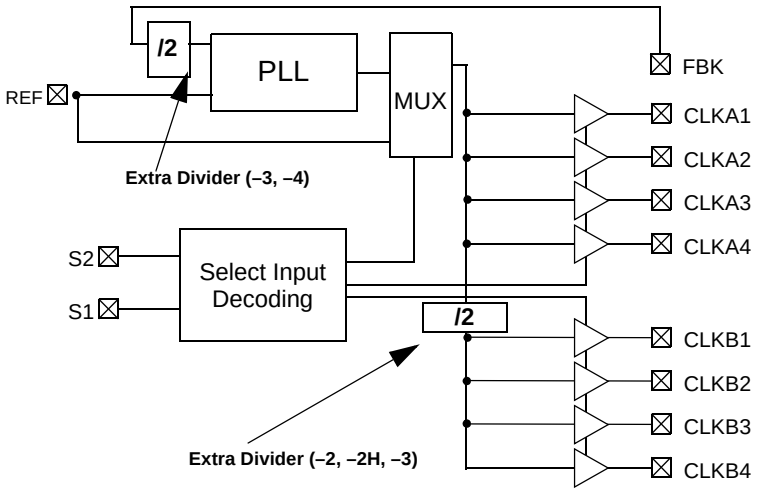
The CY23S08 is available in five different configurations, as shown in *Table 3* on page 3. The CY23S08–1 is the base part, where the output frequencies equal the reference if there is no counter in the feedback path. The CY23S08–1H is the high-drive version of the –1, and rise and fall times on this device are much faster.

The CY23S08–2 enables the user to obtain 2X and 1X frequencies on each output bank. The exact configuration and output frequencies depends on which output drives the feedback pin. The CY23S08–2H is the high-drive version of the –2, and rise and fall times on this device are much faster.

The CY23S08–3 enables the user to obtain 4X and 2X frequencies on the outputs.

The CY23S08–4 enables the user to obtain 2X clocks on all outputs. Thus, the part is extremely versatile, and can be used in a variety of applications.

Logic Block Diagram



Pinouts

Figure 1. Pin Diagram - 16 Pin SOIC Package

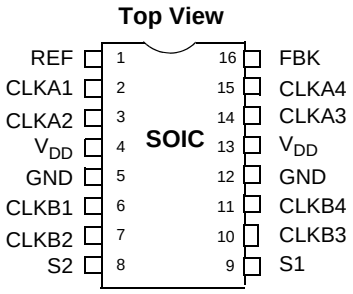


Table 1. Pin Definition - 16 Pin SOIC Package

Pin	Signal	Description
1	REF[2]	Input reference frequency, 5V tolerant input
2	CLKA1[3]	Clock output, Bank A
3	CLKA2[3]	Clock output, Bank A
4	V_{DD}	3.3V supply
5	GND	Ground
6	CLKB1[3]	Clock output, Bank B
7	CLKB2[3]	Clock output, Bank B
8	S2[4]	Select input, bit 2
9	S1[4]	Select input, bit 1
10	CLKB3[3]	Clock output, Bank B
11	CLKB4[3]	Clock output, Bank B
12	GND	Ground
13	V_{DD}	3.3V supply
14	CLKA3[3]	Clock output, Bank A
15	CLKA4[3]	Clock output, Bank A
16	FBK	PLL feedback input

Notes
1. Output phase is indeterminant (0° or 180° from input clock). If phase integrity is required, use the CY23S08–2.
2. Weak pull down.
3. Weak pull down on all outputs.
4. Weak pull ups on these inputs.

[+] Feedback

Table 2. Select Input Decoding

S2	S1	CLOCK A1–A4	CLOCK B1–B4	Output Source	PLL Shutdown
0	0	Three-State	Three-State	PLL	Y
0	1	Driven	Three-State	PLL	N
1	0	Driven	Driven	Reference	Y
1	1	Driven	Driven	PLL	N

Table 3. Available CY23S08 Configurations

Device	Feedback From	Bank A Frequency	Bank B Frequency
CY23S08–1	Bank A or Bank B	Reference	Reference
CY23S08–1H	Bank A or Bank B	Reference	Reference
CY23S08–2	Bank A	Reference	Reference/2
CY23S08–2H	Bank A	Reference	Reference/2
CY23S08–2	Bank B	2 X Reference	Reference
CY23S08–2H	Bank B	2 X Reference	Reference
CY23S08–3	Bank A	2 X Reference	Reference or $\overline{\text{Reference}}$[1]
CY23S08–3	Bank B	4 X Reference	2 X Reference
CY23S08–4	Bank A or Bank B	2 X Reference	2 X Reference

Spread Aware

Many systems being designed now utilize a technology called Spread Spectrum Frequency Timing Generation. Cypress has been one of the pioneers of SSFTG development, and we designed this product so as not to filter off the Spread Spectrum feature of the Reference input, assuming it exists. When a zero delay buffer is not designed to pass the SS feature through, the result is a significant amount of tracking skew which may cause problems in systems requiring synchronization.

For more details on Spread Spectrum timing technology, please see Cypress's application note *EMI Suppression Techniques with Spread Spectrum Frequency Timing Generator (SSFTG) ICs*.

Maximum Ratings

Supply Voltage to Ground Potential.....–0.5V to +7.0V
DC Input Voltage (Except Ref) .....–0.5V to V_{DD} + 0.5V
DC Input Voltage REF .....–0.5 to 7V
Storage Temperature .....–65°C to +150°C
Max. Soldering Temperature (10 sec.) ..... 260°C
Junction Temperature ..... 150°C
Static Discharge Voltage
(per MIL-STD-883, Method 3015) .....>2000V

Operating Conditions for CY23S08SC-XX Commercial Temperature Devices

Parameter[5]	Description	Min	Max	Unit
V_{DD}	Supply Voltage	3.0	3.6	V
T_A	Operating Temperature (Ambient Temperature)	0	70	°C
C_L	Load Capacitance, below 100 MHz	—	30	pF
	Load Capacitance, from 100 MHz to 133 MHz	—	15	pF
C_{IN}	Input Capacitance[6]	—	7	pF

Electrical Characteristics for CY23S08SC-XX Commercial Temperature Devices

Parameter	Description	Test Conditions	Min	Max	Unit
V_{IL}	Input LOW Voltage		—	0.8	V
V_{IH}	Input HIGH Voltage		2.0	—	V
I_{IL}	Input LOW Current	V_{IN} = 0V	—	50.0	µA
I_{IH}	Input HIGH Current	V_{IN} = V_{DD}	—	100.0	µA
V_{OL}	Output LOW Voltage[7]	I_{OL} = 8 mA (–1, –2, –3, –4) I_{OL} = 12 mA (-1H, -2H)	—	0.4	V
V_{OH}	Output HIGH Voltage[7]	I_{OH} = –8 mA (–1, –2, –3, –4) I_{OH} = –12 mA (–1H, –2H)	2.4	—	V
I_{DD} (PD mode)	Power down Supply Current	REF = 0 MHz	—	12.0	µA
I_{DD}	Supply Current	Unloaded outputs, 100-MHz REF, Select inputs at V_{DD} or GND	—	45.0	mA
			—	70.0 (–1H, –2H)	mA
		Unloaded outputs, 66-MHz REF (–1,–2,–3,–4)	—	32.0	mA
		Unloaded outputs, 33-MHz REF (–1,–2,–3,–4)	—	18.0	mA

Switching Characteristics for CY23S08SC-XX Commercial Temperature Devices

Parameter[8]	Name	Test Conditions	Min	Typ.	Max	Unit
t1	Output Frequency	30-pF load, –1, –1H, –2, –3 devices	10	—	100	MHz
t1	Output Frequency	30-pF load, –4 devices	15	—	100	MHz
t1	Output Frequency	20-pF load, –1H device	10	—	133.3	MHz
t1	Output Frequency	15-pF load, –1, –2, –3, devices	10	—	140.0	MHz
t1	Output Frequency	15-pF load, –4 devices	15	—	140.0	MHz
	Duty Cycle[7] = $t_2 \div t_1$ (–1,–2,–3,–4,–1H, -2H)	Measured at V_{DD}/2, F_{OUT} = 66.66 MHz 30-pF load	40.0	50.0	60.0	%
	Duty Cycle[7] = $t_2 \div t_1$ (–1,–2,–3,–4,–1H, -2H)	Measured at V_{DD}/2, F_{OUT} <66.66 MHz 15-pF load	45.0	50.0	55.0	%

Notes
5. Multiple Supplies: The voltage on any input or IO pin cannot exceed the power pin during power up. Power supply sequencing is NOT required.
6. Applies to both Ref Clock and FBK.
7. Parameter is guaranteed by design and characterization. Not 100% tested in production.
8. All parameters are specified with loaded outputs.

[+] Feedback

Switching Characteristics for CY23S08SC-XX Commercial Temperature Devices (continued)

Parameter[8]	Name	Test Conditions	Min	Typ.	Max	Unit
t3	Rise Time[7] (–1, –2, –3, –4)	Measured between 0.8V and 2.0V, 30-pF load	—	—	2.20	ns
t3	Rise Time[7] (–1, –2, –3, –4)	Measured between 0.8V and 2.0V, 15-pF load	—	—	1.50	ns
t3	Rise Time[7] (–1H, -2H)	Measured between 0.8V and 2.0V, 30-pF load	—	—	1.50	ns
t_4	Fall Time[7] (–1, –2, –3, –4)	Measured between 0.8V and 2.0V, 30-pF load	—	—	2.20	ns
t_4	Fall Time[7] (–1, –2, –3, –4)	Measured between 0.8V and 2.0V, 15-pF load	—	—	1.50	ns
t_4	Fall Time[7] (–1H, 2H)	Measured between 0.8V and 2.0V, 30-pF load	—	—	1.25	ns
t_5	Output to Output Skew on same Bank (–1)[7]	All outputs equally loaded		45	200	ps
	Output to Output Skew on same Bank (–1H,–2,–2H,–3)[7]	All outputs equally loaded	—	105	150	ps
	Output to Output Skew on same Bank (–4)[7]	All outputs equally loaded	—	70	100	ps
	Output to Output Skew (–1H, -2H)	All outputs equally loaded	—	—	200	ps
	Output Bank A to Output Bank B Skew (–1,–2, –3)	All outputs equally loaded	—	—	300	ps
	Output Bank A to Output Bank B Skew (–4)	All outputs equally loaded	—	—	215	ps
	Output Bank A to Output Bank B Skew (–1H)	All outputs equally loaded	—	—	250	ps
t_6	Delay, REF Rising Edge to FBK Rising Edge[7]	Measured at $V_{DD}/2$	–250	—	+275	ps
t_7	Device to Device Skew[7]	Measured at $V_{DD}/2$ on the FBK pins of devices	—	—	700	ps
t_8	Output Slew Rate[7]	Measured between 0.8V and 2.0V on –1H, –2H device using Test Circuit #2	1	—		V/ns
t_J	Cycle to Cycle Jitter[7] (–1, –1H)	Measured at 66.67 MHz, loaded outputs, 15, 30-pF loads: 133 MHz, 15-pF load	—	65	125	ps
	Cycle to Cycle Jitter[7] (–2)	Measured at 66.67 MHz, loaded outputs, 15-pF load	—	85	300	ps
	Cycle to Cycle Jitter[7] (–2)	Measured at 66.67 MHz, loaded outputs, 30-pF load	—	—	400	ps
t_J	Cycle to Cycle Jitter[7] (–3,–4)	Measured at 66.67 MHz, loaded outputs 15, 30-pF loads	—	—	200	ps
t_{LOCK}	PLL Lock Time[7]	Stable power supply, valid clocks presented on REF and FBK pins	—	—	1.0	ms

[+] Feedback

Switching Waveforms

Figure 2. Duty Cycle Timing

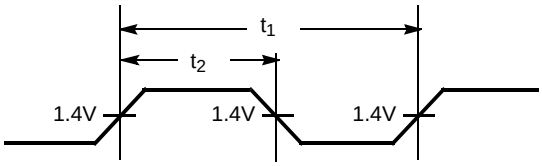


Figure 3. All Outputs Rise/Fall Time

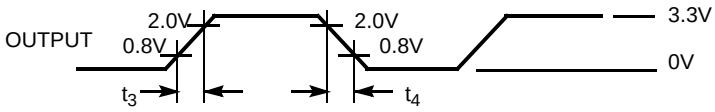


Figure 4. Output-Output Skew

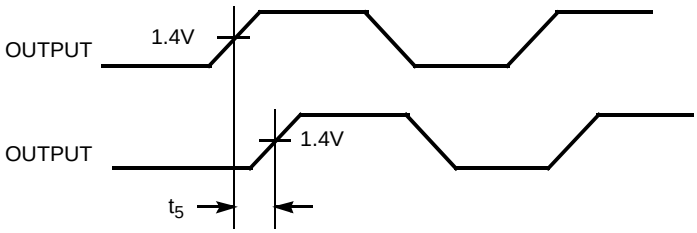


Figure 5. Input-Output Propagation Delay

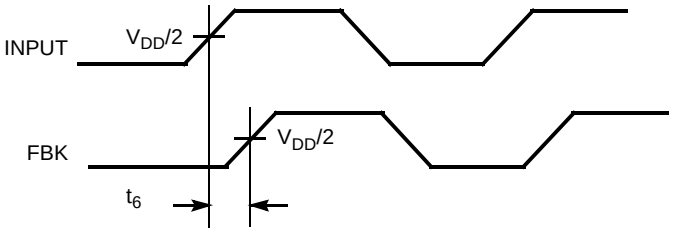
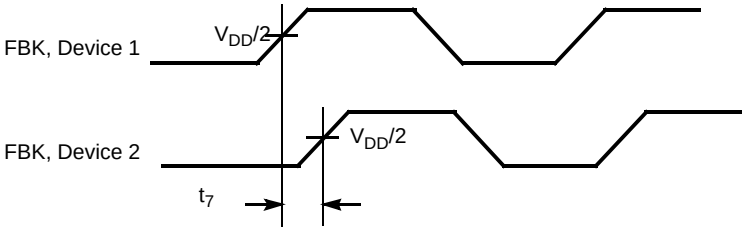
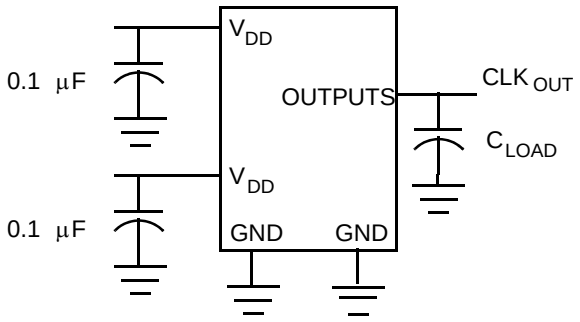


Figure 6. Device-Device Skew



Test Circuits

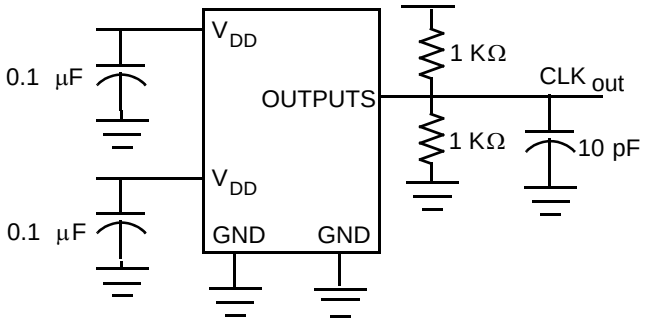
Figure 7. Test Circuit #1



Test Circuit for all parameters except t_8

Figure 8. Test Circuit #2

Test Circuit # 2



Test Circuit for t_8, Output slew rate on –1H device

Ordering Information

Ordering Code	Package Type	Operating Range	Status
CY23S08SC–1	16-pin 150-mil SOIC	Commercial	Obsolete
CY23S08SC–1T	16-pin 150-mil SOIC–Tape and Reel	Commercial	Obsolete
CY23S08SI–1	16-pin 150-mil SOIC	Industrial	Obsolete
CY23S08SI–1T	16-pin 150-mil SOIC–Tape and Reel	Industrial	Obsolete
CY23S08SC–1H	16-pin 150-mil SOIC	Commercial	Obsolete
CY23S08SC–1HT	16-pin 150-mil SOIC–Tape and Reel	Commercial	Obsolete
CY23S08SI–1H	16-pin 150-mil SOIC	Industrial	Not for new design
CY23S08SI–1HT	16-pin 150-mil SOIC–Tape and Reel	Industrial	Not for new design
CY23S08ZC–1H	16-pin 150-mil TSSOP	Commercial	Not for new design
CY23S08ZC–1HT	16-pin 150-mil TSSOP–Tape and Reel	Commercial	Obsolete
CY23S08SC–2	16-pin 150-mil SOIC	Commercial	Not for new design
CY23S08SC–2T	16-pin 150-mil SOIC–Tape and Reel	Commercial	Not for new design
CY23S08SI–2	16-pin 150-mil SOIC	Industrial	Not for new design
CY23S08SI–2T	16-pin 150-mil SOIC–Tape and Reel	Industrial	Not for new design
CY23S08SC–2H	16-pin 150-mil SOIC	Commercial	Obsolete
CY23S08SC–2HT	16-pin 150-mil SOIC–Tape and Reel	Commercial	Active
CY23S08SC–3	16-pin 150-mil SOIC	Commercial	Obsolete
CY23S08SC–3T	16-pin 150-mil SOIC–Tape and Reel	Commercial	Obsolete
CY23S08SC–4	16-pin 150-mil SOIC	Commercial	Obsolete
CY23S08SC–4T	16-pin 150-mil SOIC–Tape and Reel	Commercial	Obsolete
CY23S08SI–4	16-pin 150-mil SOIC	Industrial	Obsolete
CY23S08SI–4T	16-pin 150-mil SOIC–Tape and Reel	Industrial	Obsolete
Pb-free			
CY23S08SXC–1	16-pin 150-mil SOIC	Commercial	Active
CY23S08SXC–1T	16-pin 150-mil SOIC–Tape and Reel	Commercial	Active
CY23S08SXI–1H	16-pin 150-mil SOIC	Industrial	Active
CY23S08SXI–1HT	16-pin 150-mil SOIC–Tape and Reel	Industrial	Active
CY23S08ZXC-1H	16-pin 150-mil TSSOP	Commercial	Active
CY23S08SXC–2	16-pin 150-mil SOIC	Commercial	Active
CY23S08SXC–2T	16-pin 150-mil SOIC–Tape and Reel	Commercial	Active
CY23S08SXC–2H	16-pin 150-mil SOIC	Commercial	Active
CY23S08SXC–2HT	16-pin 150-mil SOIC–Tape and Reel	Commercial	Active
CY23S08SXI–2	16-pin 150-mil SOIC	Industrial	Active
CY23S08SXI–2T	16-pin 150-mil SOIC–Tape and Reel	Industrial	Active
CY23S08SXC-4	16-pin 150-mil SOIC	Commercial	Active
CY23S08SXC-4T	16-pin 150-mil SOIC–Tape and Reel	Commercial	Active
CY23S08SXI-4	16-pin 150-mil SOIC	Industrial	Active
CY23S08SXI-4T	16-pin 150-mil SOIC–Tape and Reel	Industrial	Active

Package Drawings and Dimensions

Figure 9. 16-Lead (150-Mil) SOIC S16

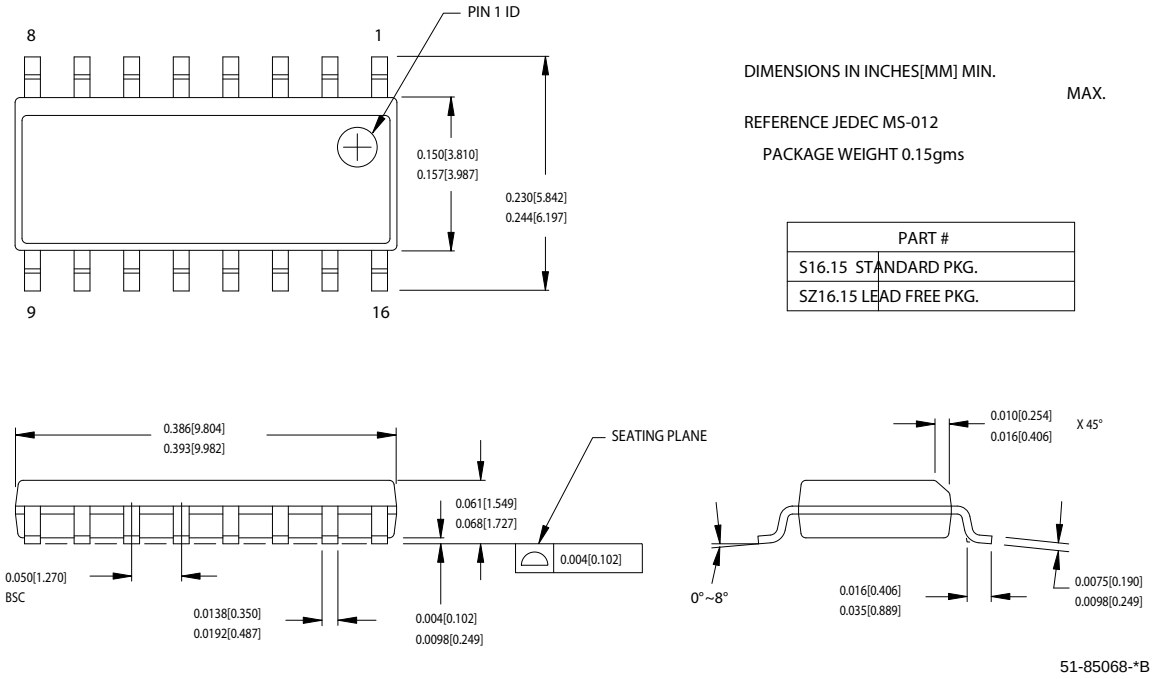
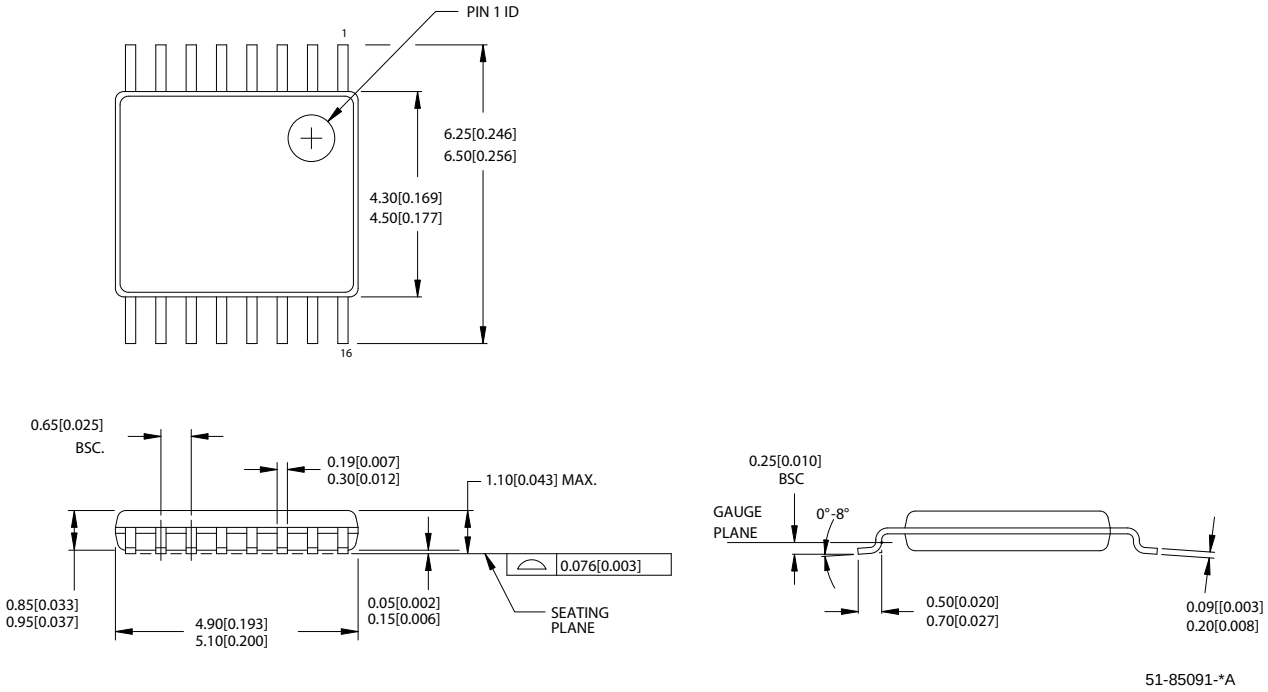


Figure 10. 16-Lead Thin Shrunk Small Outline Package (4.40 MM Body) Z16



[+] Feedback

Document History Page

Document Title: CY23S08 3.3V Zero Delay Buffer Document Number: 38-07265				
REV.	**ECN NO.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	110530	12/02/01	SZV	Change from Spec number: 38-01107 to 38-07265
*A	122863	12/20/02	RBI	Added power up requirements to operating conditions information.
*B	130951	11/26/03	RGL	Corrected the Switching Characteristics parameters to reflect the W152 device and new characterization.
*C	204201	See ECN	RGL	Corrected the Block Diagram
*D	231100	See ECN	RGL	Fixed Typo in table 2.
*E	378878	See ECN	RGL	Added Industrial Temp and Pb Free Devices Added typical char data Removed “Preliminary”
*F	391564	See ECN	RGL	Changed output-to-output skew typical value from 90ps to 45ps Added cycle-to-cycle jitter (-2) typical value of 85ps
*G	1442823	See ECN	WWZ/AESA	Updated ordering info with status update. Added new Pb-free part numbers.

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